

May 2009

FSA2257 Low R_{ON} Low-Voltage Dual SPDT Bi-Directional Analog Switch

Features

- Maximum 1.15Ω On Resistance (R_{ON}) for 4.5V Supply
- 0.3Ω Maximum R_{ON} Flatness for +5V Supply
- Space-Saving MicroPak™ Packaging
- Broad V_{CC} Operating Range: 1.65V to 5.5V
- Fast Turn-on / Turn-off Time
- Break-Before-Make Enable Circuitry
- Over-Voltage Tolerant TTL-Compatible Control Input

Description

The FSA2257 is a high-performance bi-directional dual Single-Pole/Double-Throw (SPDT) analog switch. This switch can be configured as either a multiplexer or a demultiplexer by select pins. The device features ultra-low R_{ON} of 1.3Ω maximum at 4.5V V_{CC} and operates over the wide V_{CC} range of 1.65V to 5.5V. The device is fabricated with submicron CMOS technology to achieve fast switching speeds and is designed for break-before-make operation. The select input is TTL-level compatible.

Applications

- Cell Phone
- PDA
- Mobile Devices

Ordering Information

Part Number	Package Number	Eco Status	Top Mark	Package Description	Packing Method
FSA2257L10X	MAC010A	RoHS	EP	10-Lead MicroPak™, 1.6 x 2.1mm	5000 Units on Tape and Reel
FSA2257MTCX	MTC14	RoHS	FSA2257	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	2500 Units on Tape and Reel
FSA2257MUX	MUA101A	RoHS	FSA 2257	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm	4000 Units on Tape and Reel



For Fairchild's definition of Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

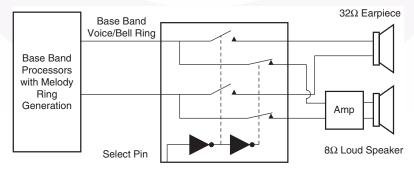
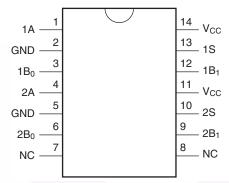


Figure 1. Block Diagram

Connection Diagrams



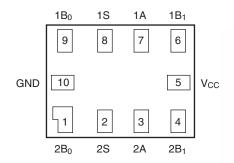


Figure 2. Pin Assignments for TSSOP (Top View)

Figure 3. Pad Assignments for MicroPak (Top View)

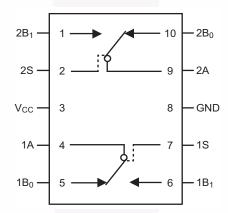
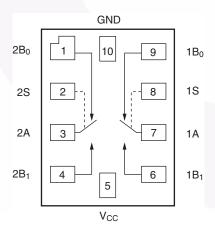


Figure 4. Pin Assignments for MSOP (Top View)

Analog Symbols



Truth Table

Control Input(s)	Function
LOW Logic Level	B ₀ Connected to A
HIGH Logic Level	B ₁ Connected to A

Pin Descriptions

Pin Names	Function
A, B ₀ , B ₁	Data Ports
S	Control Input

Figure 5. Analog Symbols (Top Through View)

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V _{CC}	Supply Voltage	-0.5	+6.0	V
V _{SW}	DC Switch Voltage ⁽²⁾	-0.5	V _{CC} +0.5	V
V _{IN}	DC Input Voltage ⁽²⁾	-0.5	+6.0	V
	Input Diode Current	-50		
I _{IK}	Switch Current		200	mA
	Peak Switch Current (Pulsed at 1ms duration, <10% duty cycle)		400	
T _{STG}	Storage Temperature Range	-65	+150	°C
TJ	Maximum Junction Temperature		+150	°C
T_L	Lead Temperature (Soldering, 10 seconds)		+260	°C
ESD	Human Body Model, JESD22-A114		8000	V
ESD	Charged Device Model, JESD22-C101		2000	V

Note:

2. The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	1.65	5.50	V
V _{IN}	Control Input Voltage ⁽³⁾	0	V _{CC}	V
V _{SW}	Switch Input Voltage	0	V _{CC}	V
T _A	Operating Temperature	-40	+85	°C

Note:

3. Unused control inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

All typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V _{CC} (V)	Т	=+25°	С		40°C to 5°C	Units	
				Min.	Тур.	Max.	Min.	Max.		
			1.8 to 2.7				1.0			
V_{IH}	Input Voltage High		2.7 to 3.6				2.0		V	
			4.5 to 5.5				2.4			
			1.8 to 2.7					0.4		
V_{IL}	Input Voltage Low		2.7 to 3.6					0.6	V	
			4.5 to 5.5					0.8		
1	Control Input Lookaga	\/ = 0\/ to \/	2.7 to 3.6		A		-1.0	1.0	^	
I _{IN}	Control Input Leakage	$V_{IN} = 0V \text{ to } V_{CC}$	4.5 to 5.5				-1.0	1.0	μΑ	
I _{NO(OFF)} , I _{NC(OFF)}	Off-Leakage Current of Port B ₀ and B ₁	A = 1V, 4.5V, B ₀ or B ₁ = 1V, 4.5V	5.5	-2.0		2.0	-20.0	20.0	nA	
I _{A(ON)}	On Leakage Current of Port A	A = 1V, 4.5V, B_0 or $B_1 = 1V, 4.5V$ or Floating	5.5	-4.0		4.0	-40.0	40.0	nA	
		- 400mA D anD - 4.5V	1.8		4.6					
	Switch ON Resistance MicroPak ⁽⁴⁾	$I_{OUT} = 100 \text{mA}, B_0 \text{ or } B_1 = 1.5 \text{V}$	2.7		2.6	4.0		4.3		
R _{ON}	Wildred aix	$I_{OUT} = 100 \text{mA}, B_0 \text{ or } B_1 = 3.5 \text{V}$	4.5		0.95	1.15		1.30	Ω	
	Switch On Resistance	$I_{OUT} = 100 \text{mA}, B_0 \text{ or } B_1 = 1.5 \text{V}$	2.7		2.8			4.5		
	MSOP / TSSOP ⁽⁴⁾	$I_{OUT} = 100$ mA, B_0 or $B_1 = 3.5$ V	4.5		1.5			2.3		
	On Resistance Matching 5etween Channels ⁽⁴⁾ MicroPak	I _{OUT} = 100mA, B ₀ or B ₁ = 3.5V	4.5		0.06	0.12		0.15		
ΔR_{ON}	On Resistance Matching Between Channels ⁽⁵⁾ MSOP / TSSOP	I _{OUT} = 100mA, B ₀ or B ₁ = 3.5V	4.5		0.7			0.3	Ω	
		$I_{OUT} = 100 \text{mA}, B_0 \text{ or } B_1 = 0 \text{V},$	1.8		3.0					
R _{FLAT(ON)}	On Resistance	0.75V, 1.5V	2.7		1.4				Ω	
· FLAT(UN)	Flatness ⁽⁶⁾	I _{OUT} = 100mA, B ₀ or B ₁ = 0V, 1V, 2V	4.5		0.2	0.3		0.4		
	Quiescent Supply	\\ = 0\\ or \\ \ \ = 0\\	3.6		0.1	0.5		1.0	^	
I _{CC}	Current	$V_{IN} = 0V \text{ or } V_{CC}, I_{OUT} = 0V$ 5.5 0.1 0.4	0.5		1.30 4.5 2.3 0.15 0.3	μΑ				

Notes:

- 4. On resistance is determined by the voltage drop between A and B pins at the indicated current through the switch.
- 5. ΔR_{ON} = $R_{ONmax} R_{ONmin}$ measured at identical V_{CC} , temperature, and voltage.
- 6. Flatness is defined as the difference between the maximum and minimum value of on resistance over the specified range of conditions.

AC Electrical Characteristics

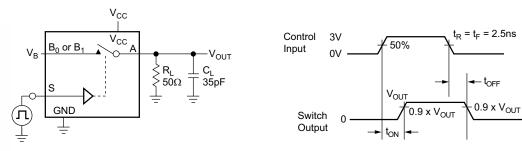
All typical values are at 25°C unless otherwise specified.

Cumbal	Parameter	Conditions	V (V)	Т	T _A =+25°C			40°C to	+85°C	Figure	
Symbol	Parameter	Conditions	V _{CC} (V)	Min.	Тур.	Max.	Min.	Max.	Units	Number	
		$B_0 \text{ or } B_1 = 1.5 \text{V},$	1.8 to 2.7		75						
t _{ON}	Turn-On Time	$R_L = 50\Omega, C_L = 35pF$	2.7 to 3.6			50		60	ns	Figure 6.	
JON		$B_0 \text{ or } B_1 = 3.0 \text{V},$ $R_L = 50 \Omega, C_L = 35 \text{pF}$	4.5 to 5.5			35		40		r iguro o.	
		B_0 or $B_1 = 1.5V$,	1.8 to 2.7		20						
t _{OFF}	Turn-Off Time	$R_L = 50\Omega, C_L = 35pF$	2.7 to 3.6			20		30	ns	Figure 6.	
OFF		$B_0 \text{ or } B_1 = 3.0 \text{V},$ $R_L = 50 \Omega, C_L = 35 \text{pF}$	4.5 to 5.5			15		20			
	Break-Before-	$B_0 \text{ or } B_1 = 1.5V,$ $R_L = 50\Omega, C_L = 35pF$	2.7 to 3.6	3.6		1			Figure 7		
t _{BBM}	Make Time	$B_0 \text{ or } B_1 = 3.0 \text{V},$ $R_L = 50 \Omega, C_L = 35 \text{pF}$	4.5 to 5.5		20		1		ns	Figure 7.	
Q	Charge Injection	$C_L = 1.0 nF, V_{GEN} = 0 V,$	2.7 to 3.6		20				nC	Figure 9.	
Q	Charge injection	$R_{GEN} = 0\Omega$	4.5 to 5.5		10				pC	Figure 9.	
OIRR	Off Inclation	Off Isolation	$f = 1MHz, R_L = 50\Omega$	2.7 to 3.6		-70				dB	Figure 8.
OIKK	Oli isolation	1 - 1W112, K[- 3052	4.5 to 5.5		-70				uБ	rigule 6.	
Xtalk	Crosstalk	$f = 1MHz, R_1 = 50\Omega$	2.7 to 3.6		-75				dB	Figure 8.	
Xtaix	Orossiaik	1 - 1W112, 11 - 3032	4.5 to 5.5		-75				QD.	riguic o.	
BW	-3db Bandwidth	$R_1 = 50\Omega$	2.7 to 3.6		200				MHz	Figure 11.	
DVV	Odb Ballawidti	11 0022	4.5 to 5.5		200				1011 12	riguic 11.	
THD	Total Harmonic	$R_L = 600\Omega, V_{IN} = 0.5V_{PP}$	2.7 to 3.6		0.002				%	Figure 12.	
1110	Distortion	f = 20Hz to 20kHz	4.5 to 5.5		0.002				/0	riguic 12.	

Capacitance

Symbol Parameter		Conditions	V _{CC} (V)	T	T _A =+25°C		5°C T _A = 40 to +8		Units	Figure
Symbol	raiailletei	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Number	
C _{IN}	Control Pin Input Capacitance	f = 1MHz	0.0		3.5				pF	Figure 10.
C _{OFF}	B Port Off Capacitance	f = 1MHz	4.5		12.0				pF	Figure 10.
C _{ON}	A Port On Capacitance	f = 1MHz	4.5		40.0				pF	Figure 10.

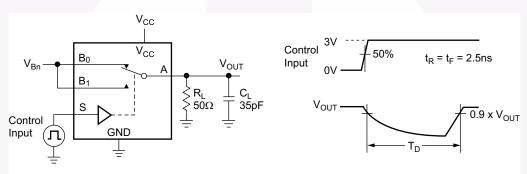
AC Loading and Waveforms



C_L Includes Fixture and Stray Capacitance

Logic Input Waveforms Inverted for Switches that have the Opposite Logic Sense

Figure 6. Turn-On / Turn-Off Timing



C_L Includes Fixture and Stray Capacitance

Figure 7. Break-Before-Make Timing

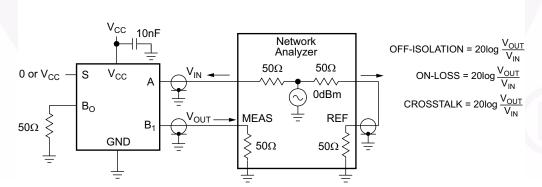


Figure 8. Off Isolation and Crosstalk

AC Loading and Waveforms (Continued)

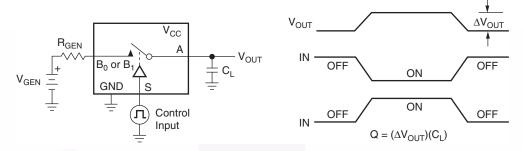


Figure 9. Charge Injection

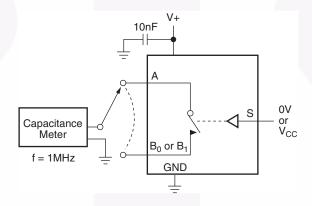


Figure 10. On / Off Capacitance Measurement Setup

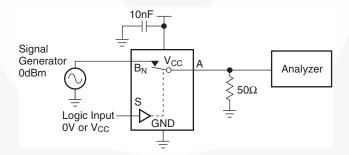


Figure 11. Bandwidth

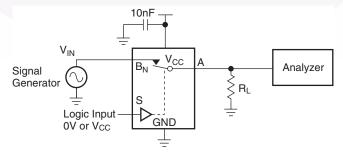
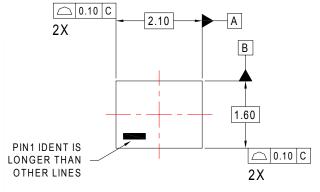
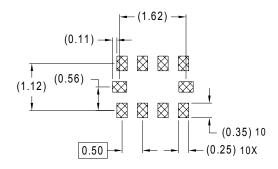


Figure 12. Harmonic Distortion

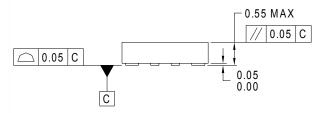
Physical Dimensions



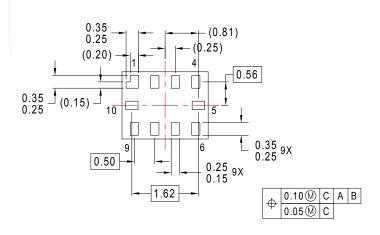
TOP VIEW



RECOMMENDED LAND PATTERN



SIDE VIEW



NOTES:

- A. PACKAGE CONFORMS TO JEDEC REGISTRATION MO-255, VARIATION UABD
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. DRAWING FILENAME: MKT-MAC10Arev4.

BOTTOM VIEW

Figure 13. 10-Lead MicroPak, 1.6 x 2.1mm

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Note: click here for tape and reel specifications, available at: http://www.fairchildsemi.com/products/logic/pdf/micropak_tr.pdf

Physical Dimensions (Continued)

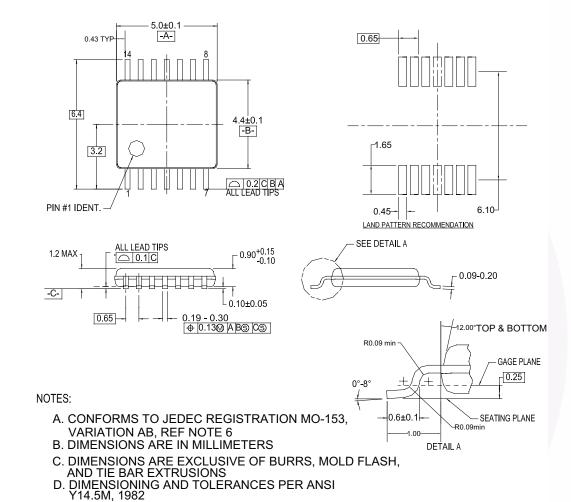


Figure 14. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

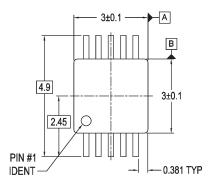
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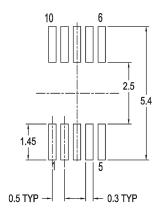
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E. LANDPATTERN STANDARD: SOP65P640X110-14M

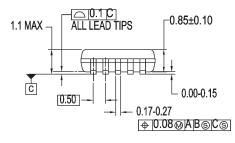
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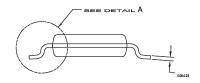
Physical Dimensions (Continued)

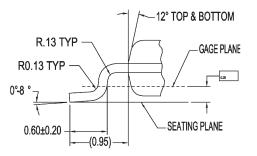




LAND PATTERN RECOMENDATION







DETAIL A

DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187, VARIATION BA, REF NOTE 6, DATE 11/00.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.

MUA10AREVA

Figure 15. 10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0m

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Datasheet Identification	Product Status	Definition
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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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